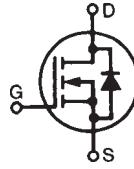


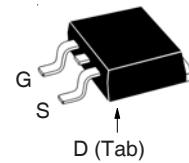
**Trench™
Power MOSFET**
**IXTA160N10T
IXTP160N10T**

V_{DSS} = 100V
I_{D25} = 160A
R_{DS(on)} ≤ 7.0mΩ

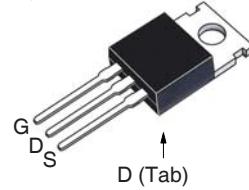
N-Channel Enhancement Mode
Avalanche Rated



TO-263
(IXTA)



TO-220
(IXTP)



G = Gate D = Drain
 S = Source Tab = Drain

Symbol	Test Conditions	Maximum Ratings		
V _{DSS}	T _J = 25°C to 175°C	100		V
V _{DGR}	T _J = 25°C to 175°C, R _{GS} = 1MΩ	100		V
V _{GSS}	Continuous	± 20		V
V _{GSM}	Transient	± 30		V
I _{D25}	T _C = 25°C (Chip Capability)	160		A
I _{L(RMS)}	Lead Current Limit, RMS	120		A
I _{DM}	T _C = 25°C, Pulse Width Limited by T _{JM}	430		A
I _A	T _C = 25°C	25		A
E _{AS}	T _C = 25°C	500		mJ
dV/dt	I _S ≤ I _{DM} , V _{DD} ≤ V _{DSS} , T _J ≤ 175°C	3		V/ns
P _D	T _C = 25°C	430		W
T _J		-55 ... +175		°C
T _{JM}		175		°C
T _{stg}		-55 ... +175		°C
T _L	Maximum Lead Temperature for Soldering	300		°C
T _{SOLD}	1.6 mm (0.062in.) from Case for 10s	260		°C
F _c	Mounting Force (TO-263)	10..65 / 2.2..14.6		N/lb
M _d	Mounting Torque (TO-220)	1.13 / 10		Nm/lb.in
Weight	TO-263	2.5		g
	TO-220	3.0		g

Symbol	Test Conditions (T _J = 25°C Unless Otherwise Specified)	Characteristic Values		
		Min.	Typ.	Max.
BV _{DSS}	V _{GS} = 0V, I _D = 250μA	100		V
V _{GS(th)}	V _{DS} = V _{GS} , I _D = 250μA	2.5		4.5 V
I _{GSS}	V _{GS} = ± 20V, V _{DS} = 0V		±200	nA
I _{DSS}	V _{DS} = V _{DSS} , V _{GS} = 0V T _J = 150°C		5 μA 250 μA	
R _{DS(on)}	V _{GS} = 10V, I _D = 25A, Notes 1& 2	6.1	7.0	mΩ

Features

- Ultra-Low On Resistance
- Avalanche Rated
- Low Package Inductance
 - Easy to Drive and to Protect
- 175°C Operating Temperature
- Fast Intrinsic Diode

Advantages

- Easy to Mount
- Space Savings
- High Power Density

Applications

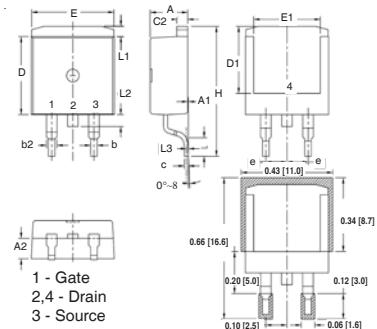
- Automotive
 - Motor Drives
 - 42V Power Bus
 - ABS Systems
- DC/DC Converters and Off-line UPS
- Primary Switch for 24V and 48V Systems
- Distributed Power Architectures and VRMs
- Electronic Valve Train Systems
- High Current Switching Applications
- High Voltage Synchronous Rectifier

Symbol	Test Conditions ($T_J = 25^\circ\text{C}$, Unless Otherwise Specified)	Characteristic Values		
		Min.	Typ.	Max.
g_{fs}	$V_{DS} = 10\text{V}$, $I_D = 60\text{A}$, Note 1	65	102	S
C_{iss} C_{oss} C_{rss}	$V_{GS} = 0\text{V}$, $V_{DS} = 25\text{V}$, $f = 1\text{MHz}$	6600		pF
		880		pF
		135		pF
$t_{d(on)}$ t_r $t_{d(off)}$ t_f	Resistive Switching Times $V_{GS} = 10\text{V}$, $V_{DS} = 0.5 \cdot V_{DSS}$, $I_D = 25\text{A}$ $R_G = 5\Omega$ (External)	33		ns
		61		ns
		49		ns
		42		ns
$Q_{g(on)}$ Q_{gs} Q_{gd}	$V_{GS} = 10\text{V}$, $V_{DS} = 0.5 \cdot V_{DSS}$, $I_D = 25\text{A}$	132		nC
		37		nC
		40		nC
R_{thJC}			0.35	$^\circ\text{C}/\text{W}$
R_{thCH}	TO-220	0.50		$^\circ\text{C}/\text{W}$

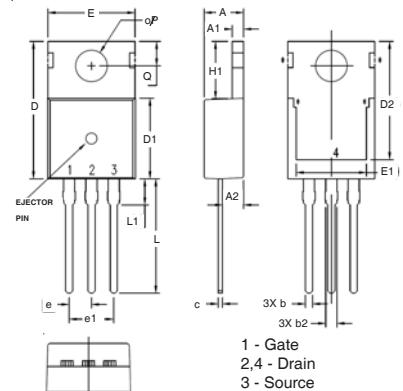
Source-Drain Diode

Symbol	Test Conditions ($T_J = 25^\circ\text{C}$, Unless Otherwise Specified)	Characteristic Values		
		Min.	Typ.	Max.
I_s	$V_{GS} = 0\text{V}$		160	A
I_{SM}	Repetitive, Pulse Width Limited by T_{JM}		430	A
V_{SD}	$I_F = 25\text{A}$, $V_{GS} = 0\text{V}$, Note 1		1.0	V
t_{rr}	$I_F = 25\text{A}$, $V_{GS} = 0\text{V}$ -di/dt = $100\text{A}/\mu\text{s}$, $V_R = 50\text{V}$	60		ns

Notes: 1. Pulse test, $t \leq 300\mu\text{s}$; duty cycle, $d \leq 2\%$.
 2. On through-hole packages, $R_{DS(on)}$ Kelvin test contact location must be 5mm or less from the package body.

TO-263 Outline


SYM	INCHES		MILLIMETER	
	MIN	MAX	MIN	MAX
A	.170	.185	4.30	4.70
A1	.000	.008	0.00	0.20
A2	.091	.098	2.30	2.50
b	.028	.035	0.70	0.90
b2	.046	.060	1.18	1.52
C	.018	.024	0.45	0.60
C2	.049	.060	1.25	1.52
D	.340	.370	8.63	9.40
D1	.300	.327	7.62	8.30
E	.380	.410	9.65	10.41
E1	.270	.330	6.86	8.38
e	.100	BSC	2.54	BSC
H	.580	.620	14.73	15.75
L	.075	.105	1.91	2.67
L1	.039	.060	1.00	1.52
L2	—	.070	—	1.77
L3	.010	BSC	0.254	BSC

TO-220 Outline


SYM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	.169	.185	4.30	4.70
A1	.047	.055	1.20	1.40
A2	.079	.106	2.00	2.70
b	.024	.039	0.60	1.00
b2	.045	.057	1.15	1.45
c	.014	.026	0.35	0.65
D	.587	.626	14.90	15.90
D1	.335	.370	8.50	9.40
(D2)	.500	.531	12.70	13.50
E	.382	.406	9.70	10.30
(E1)	.283	.323	7.20	8.20
e	.100	BSC	2.54	BSC
e1	.200	BSC	5.08	BSC
H1	.244	.268	6.20	6.80
L	.492	.547	12.50	13.90
L1	.110	.154	2.80	3.90
ØP	.134	.150	3.40	3.80
Q	.106	.126	2.70	3.20

PRELIMINARY TECHNICAL INFORMATION

The product presented herein is under development. The Technical Specifications offered are derived from data gathered during objective characterizations of preliminary engineering lots; but also may yet contain some information supplied during a pre-production design evaluation. IXYS reserves the right to change limits, test conditions, and dimensions without notice.

IXYS reserves the right to change limits, test conditions, and dimensions.

IXYS MOSFETs and IGBTs are covered by one or more of the following U.S. patents: 4,835,592 4,931,844 5,049,961 5,237,481 6,162,665 6,404,065 B1 6,683,344 6,727,585 7,005,734 B2 7,157,338B2 4,860,072 5,017,508 5,063,307 5,381,025 6,259,123 B1 6,534,343 6,710,405 B2 6,759,692 7,063,975 B2 4,881,106 5,034,796 5,187,117 5,486,715 6,306,728 B1 6,583,505 6,710,463 6,771,478 B2 7,071,537

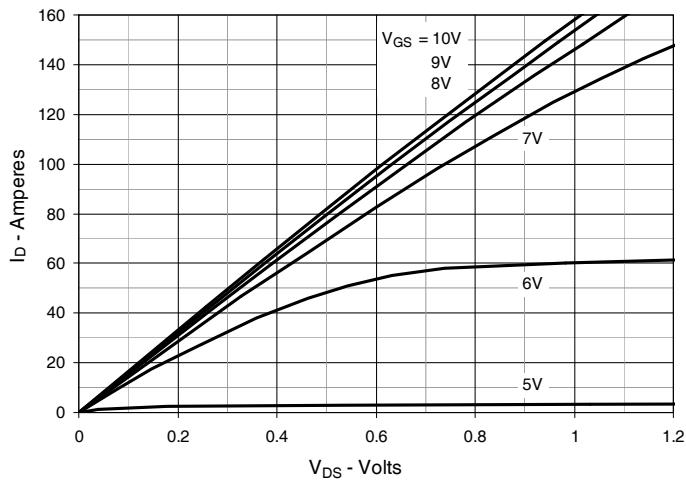
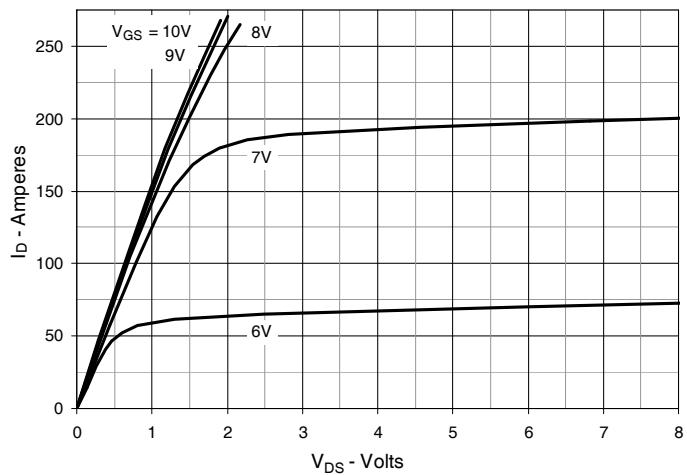
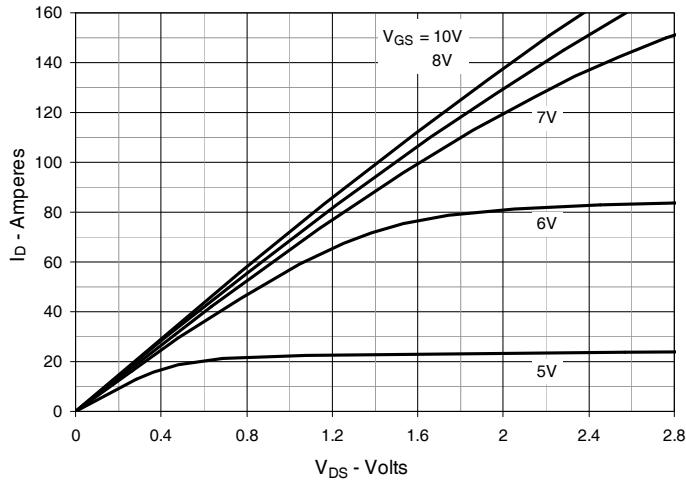
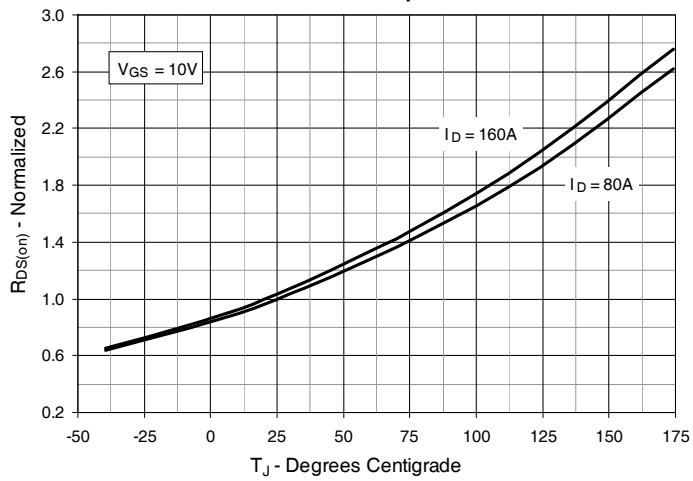
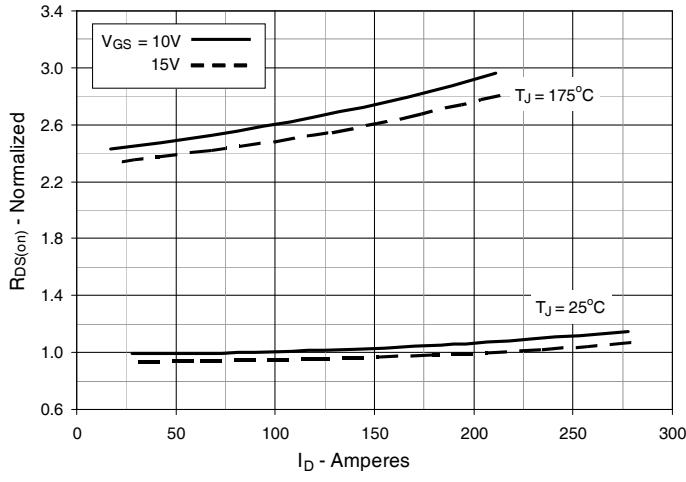
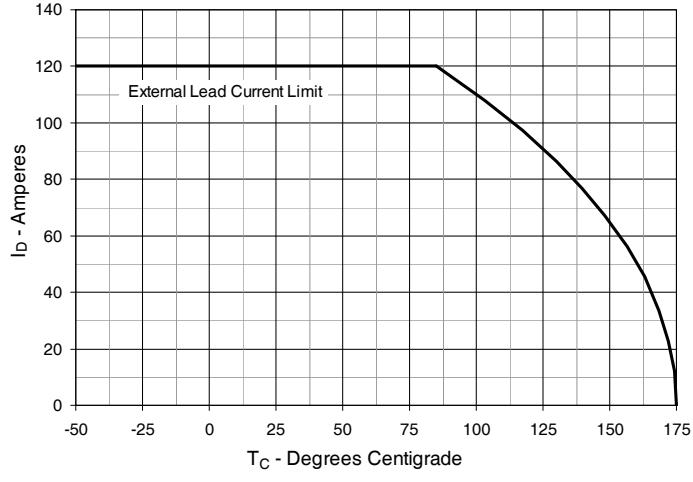
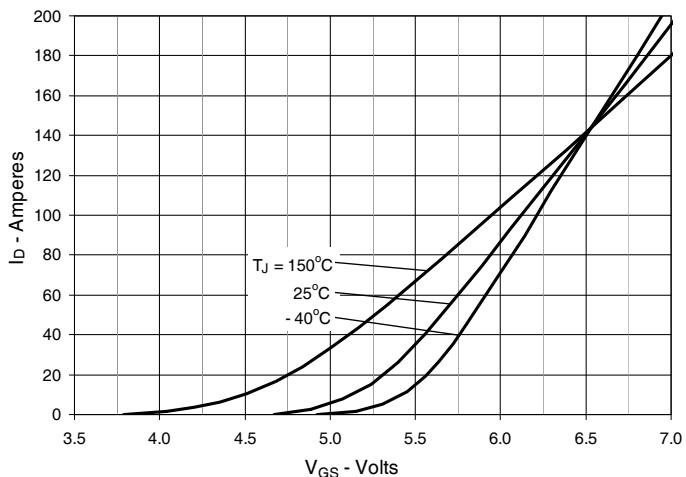
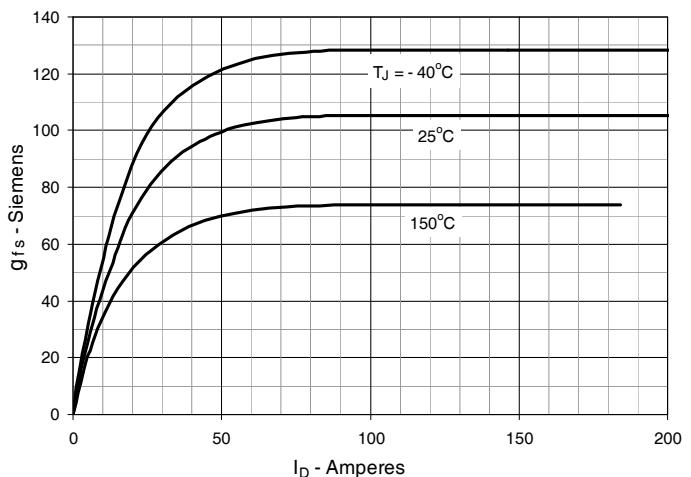
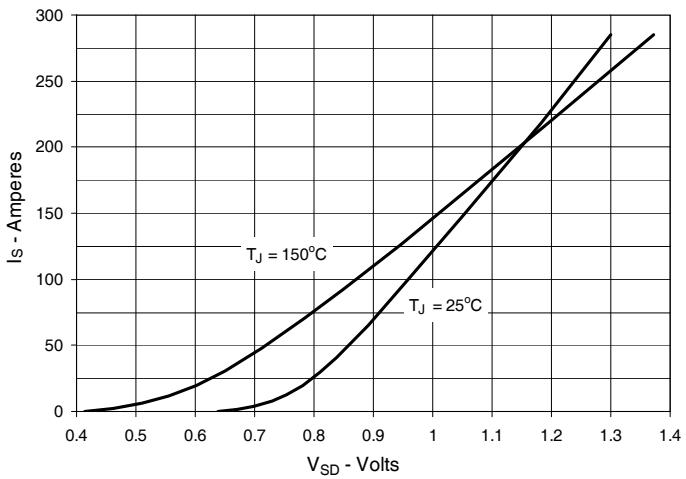
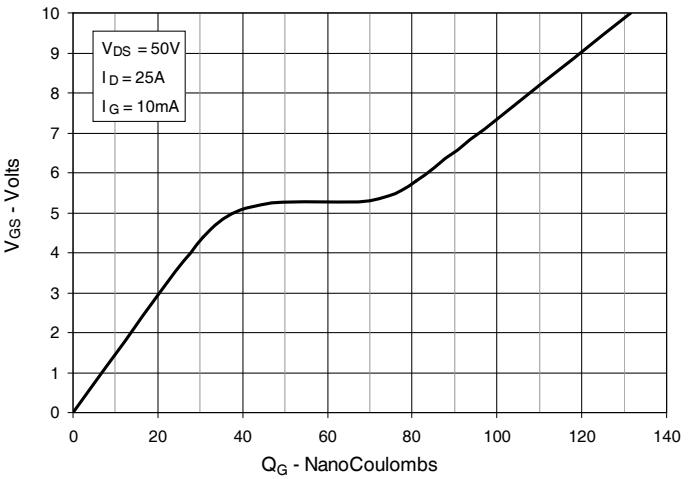
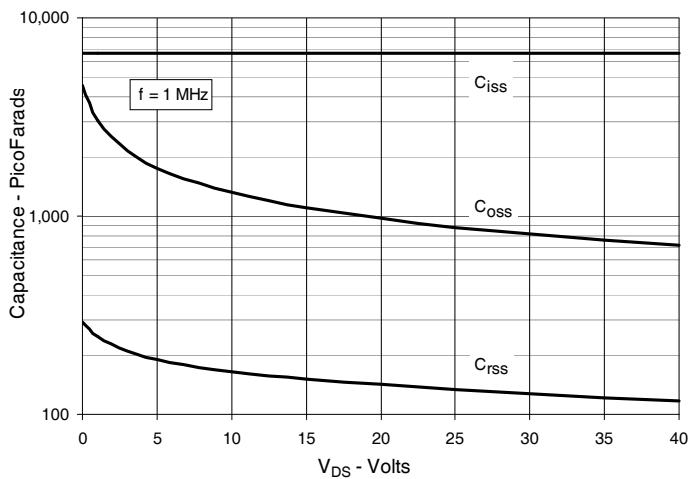
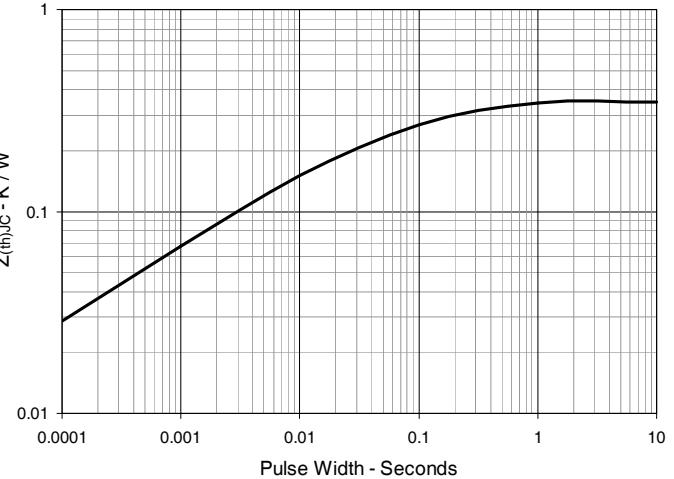
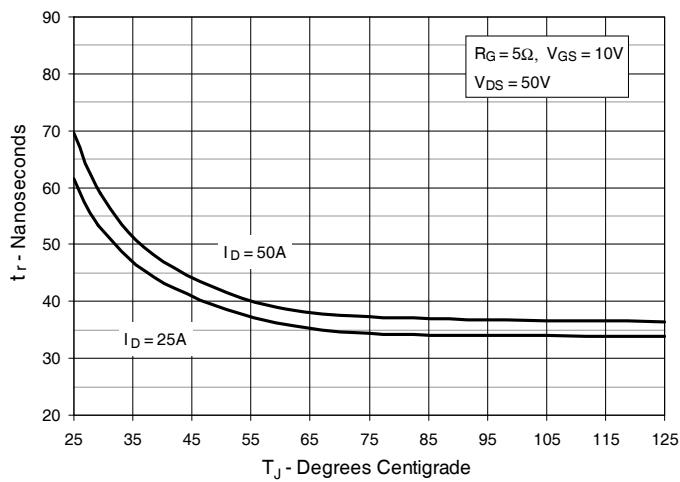
Fig. 1. Output Characteristics @ $T_J = 25^\circ\text{C}$

Fig. 2. Extended Output Characteristics @ $T_J = 25^\circ\text{C}$

Fig. 3. Output Characteristics @ $T_J = 150^\circ\text{C}$

Fig. 4. $R_{DS(on)}$ Normalized to $I_D = 160\text{A}$ Value vs. Junction Temperature

Fig. 5. $R_{DS(on)}$ Normalized to $I_D = 80\text{A}$ Value vs. Drain Current

Fig. 6. Drain Current vs. Case Temperature


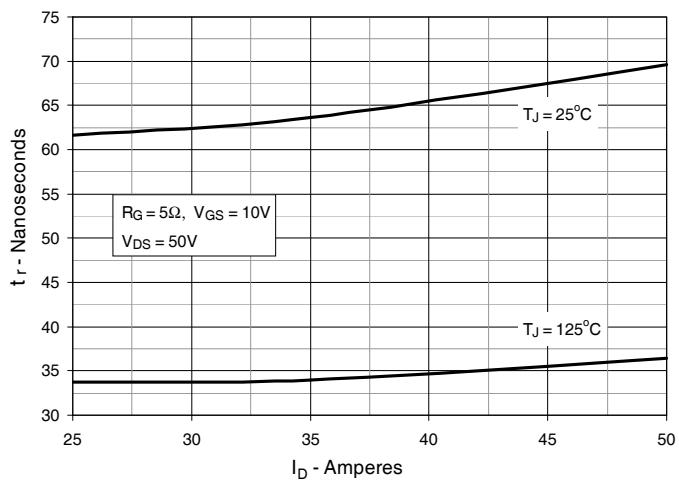
Fig. 7. Input Admittance

Fig. 8. Transconductance

Fig. 9. Forward Voltage Drop of Intrinsic Diode

Fig. 10. Gate Charge

Fig. 11. Capacitance

Fig. 12. Maximum Transient Thermal Impedance


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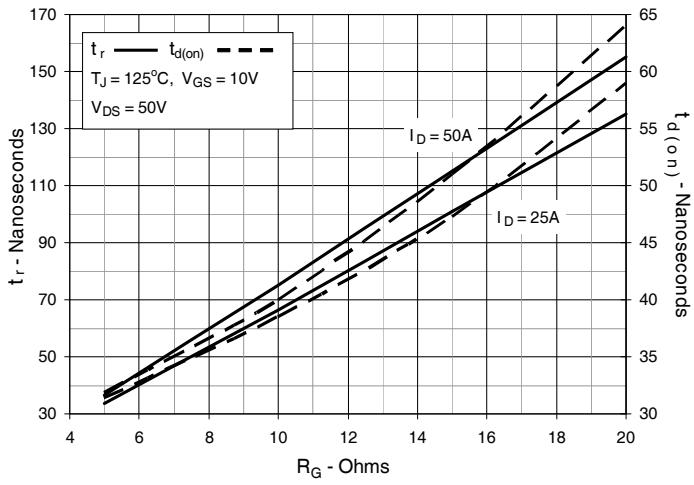
**Fig. 13. Resistive Turn-on
Rise Time vs. Junction Temperature**



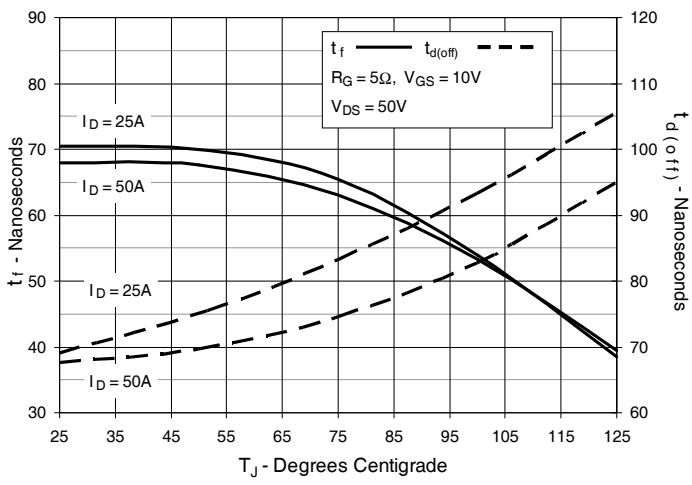
**Fig. 14. Resistive Turn-on
Rise Time vs. Drain Current**



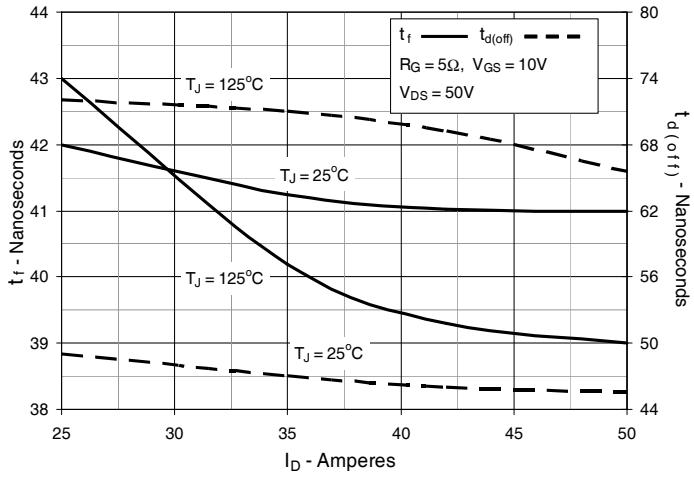
**Fig. 15. Resistive Turn-on
Switching Times vs. Gate Resistance**



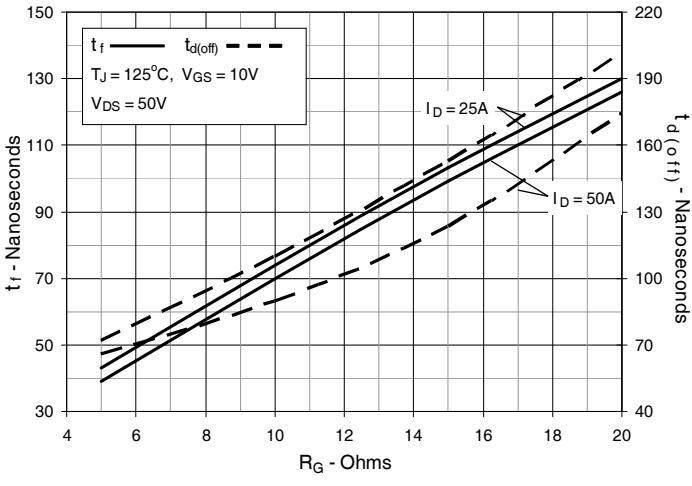
**Fig. 16. Resistive Turn-off
Switching Times vs. Junction Temperature**



**Fig. 17. Resistive Turn-off
Switching Times vs. Drain Current**



**Fig. 18. Resistive Turn-off
Switching Times vs. Gate Resistance**





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